	BLE STA	NDARD			<u></u>						
Operating temperature		e range -55 °C to 85 °C			Storage temperature range Operating or storage humidity range			-10℃ TO 50℃(Packed conditio			
RATING	Voltage		30V AC / DC				Relative humidity 90 % MAX (Not dew			ewed	
	Current		0.3 A 🖄	t=0.2±0.03mm, Gold p				plating	g		
			SPEC	CIFICA	TIONS						
ITI	EM		TEST METHOD			RE	QUIR	EMENTS	QT	A٦	
CONSTR	RUCTION										
General examination		Visually and by measuring instrument.			According to drawing.				×	×	
Marking		Confirmed visually.			(note 1)				×	×	
ELECTRICAL CHA											
Voltage proof		90 V AC for 1 min.			No flashover or breakdown.				×	-	
Insulation resistance		100 V DC.			50 mΩ MAX.				×	-	
Contact resistance		AC 20 mV MAX , 1 mA .			100 mΩ MAX. Including FPC bulk resistance. (L=8mm)				×	-	
MECHAN			RISTICS		Including 11	O Duik I	031312				
Vibration			10 to 55 Hz, half amplitude	e	(1) No elect	rical disc	ontin	uity of 1 us	×	Τ_	
	VISIAIION		0.75 mm, for 10 cycles in 3 axial directions.			<ol> <li>No electrical discontinuity of 1 μs.</li> <li>Contact resistance: 100 mΩ MAX.</li> </ol>					
Shock		981 m/s <sup>2</sup> , duration of pulse 6 ms			③ No damage, crack and looseness of parts.				×	-	
Maahaalaalaa		at 3 times in 3 both axial directions.								_	
Mechanical operation		10 times	insertions and extractions.	-	(1) Contact resistance: $100 \text{ m}\Omega \text{ MAX}$ .				-		
FPC insertion force		Measured I	by applicable FPC.		② No damage, crack and looseness of parts. Insertion force : Direction of insertion						
FPC retention force			of FPC shall be t=0.20mm		2.6+0.14 × n N MAX ( <i>note 2</i> )						
		at initial condition.)				(n: Number of contacts)					
			by applicable FPC.		Retention force : Direction of extraction						
		(Thickness at initial co	of FPC shall be t=0.20mm		5+0.07 × n N MIN ( <i>note3</i> ) (n: Number of contacts)						
			,		(n: Number	of contac	cts)				
			ACTERISTICS	45 0500						1	
Rapid change of temperature		Temperature-55 $\rightarrow$ +15 <sub>TO</sub> +35 $\rightarrow$ +85 $\rightarrow$ +15 <sub>TO</sub> +35°C Time 30 $\rightarrow$ 2 to 3 $\rightarrow$ 30 $\rightarrow$ 2 to 3 min			<ol> <li>Contact</li> <li>Insulatio</li> </ol>				×	-	
		Under 5 cycles. $30 \rightarrow 263 \rightarrow 30 \rightarrow 263$ mini			<ol> <li>No damage, crack and looseness of parts.</li> </ol>						
Damp heat		Exposed at $40\pm2$ °C,							×	-	
(steady state)		Relative humidity 90 to 95 %, 96 h.									
Damp heat,cyclic		Exposed at -10 to +65 °c, Relative humidity 90 to 96 %, 10 cycles, TOTAL 240 h.			(1) Contact resistance: $100 \text{ m}\Omega \text{ MAX}$ .				×	-	
								1 MΩ MIN. (At high humidity) 50 MΩ MIN. (At dry)			
		10 090100,			-			l looseness of parts.			
Dry heat		Exposed at 85±2°C, 96 h.			(1) Contact resistance: $100 \text{ m}\Omega$ MAX.				×	1_	
Cold		Exposed at -55±3°C, 96 h.			<ul> <li>2 No damage, crack and looseness of parts.</li> </ul>				×	- 1	
Sulphur dioxide		Exposed at $40\pm2$ °C, Relative humidity $80\pm5\%$ ,			(1) Contact resistance: 100 m $\Omega$ MAX.				×	1 -	
[JIS C 60068-2-42]		25±5 ppm <b>for</b> 96 h.									
Solderability		Soldered at solder temperature,			A new uniform coating of solder shall cover a				×	-	
Resistance to		$245\pm3^{\circ}$ C for immersion duration, $3\pm0.3$ sec. 1) Reflow soldering :			minimum of 95 % of the surface being immersed. No deformation of case of excessive looseness				×	+_	
soldering heat		Peak TMP. 250 °C MAX .			of the terminals. ( <i>note 4</i> )						
		Reflow TMP. over 220 °C 60 to 90 sec.									
			r of reflow : 2 times								
		2) Solderin	ng								
COUN			ON OF REVISIONS	1	DESIGNED			CHECKED	ר ^ח	ATE	
		DIS-F-00007424			TS. WADA			HS. HIRAHARA		20201217	
		D13-F-0000/424				4					
REMARK			One Action Lock" completes FPC loc	ck just by insertir	ng the FPC.	APPRC	VED	YN. TAKASHITA	2018	3090;	
(note1) This proc	Do not operate the locking-lever when inserting the FPC. (note2) Do not insert the FPC to this product at an angle.					CHEC	ECKED SJ. OKAMURA		20180903		
( <i>note1</i> ) This proc Do not o		his product at an	n angle.								
( <i>note1</i> ) This proc Do not op ( <i>note2</i> ) Do not in ( <i>note3</i> ) Stabilize	nsert the FPC to t the FPC to PCB	or something fix	ed, if pull-up or pull-down force is e	expected to be ap	plied to the FPC.						
( <i>note</i> 1) This proc Do not op ( <i>note</i> 2) Do not in ( <i>note3</i> ) Stabilize There's a	nsert the FPC to t the FPC to PCB a case which FPC	or something fix retention force	•	expected to be ap	pplied to the FPC.	DESIG	NED	SG. MASAK I	2018	3090	
(note1) This proc Do not of (note2) Do not in (note3) Stabilize There's a because (note4) Blisters v	nsert the FPC to to the FPC to PCB a case which FPC FPC specificatio which may be ger	or something fix c retention force n affects the residentiated on the here	ed, if pull-up or pull-down force is e doesn't fulfill the value, ult of FPC retention force. pusing do not affect product perform		plied to the FPC.	DESIG DRAV		SG. MASAKI Sg. Masaki	2018 2018		
(note1) This proc Do not op (note2) Do not in (note3) Stabilize There's a because (note4) Blisters v Unless other	nsert the FPC to to the FPC to PCB a case which FPC FPC specificatio which may be ger rwise specific	or something fix c retention force n affects the resi- nerated on the ho ed, refer to IE	ed, if pull-up or pull-down force is e doesn't fulfill the value, ult of FPC retention force. ousing do not affect product perform EC 60512.	nance.		DRAV		SG. MASAKI	2018	3090	
(note1) This proc Do not op (note2) Do not in (note3) Stabilize There's a because (note4) Blisters v Unless other Note QT:Q	nsert the FPC to to the FPC to PCB a case which FPC e FPC specificatio which may be ger rwise specific Qualification T	or something fix c retention force n affects the resi- nerated on the ho ed, refer to IE rest AT:Ass	ed, if pull-up or pull-down force is e doesn't fulfill the value, ult of FPC retention force. ousing do not affect product perform EC 60512. surance Test X:Applicable	nance. Test	DRAWIN	DRAV	VN	sg. masaki ELC-382927-0	2018	3090	
(note1) This proc Do not op (note2) Do not in (note3) Stabilize There's a because (note4) Blisters v Unless other	nsert the FPC to t the FPC to PCB a case which FPC e FPC specificatio which may be ger rwise specific Qualification T	or something fix c retention force in affects the resi- nerated on the ho ed, refer to IE rest AT:Ass SPECIFI	ed, if pull-up or pull-down force is e doesn't fulfill the value, ult of FPC retention force. ousing do not affect product perform EC 60512.	nance.		DRAV	VN	sg. masaki ELC-382927-0 FH72-**S-0. 3SHW	2018 0-0(	3090;	